

RCJ220N25

Nch 250V 22A Power MOSFET

V_{DSS}	250V
R _{DS(on)} (Max.)	140m Ω
I _D	22A
P_D	166W

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

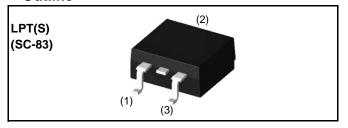
Application

Switching Power Supply

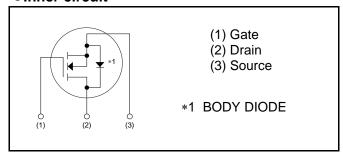
Automotive Motor Drive

Automotive Solenoid Drive

Outline



●Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Type	Tape width (mm)	24
Type	Quantity (pcs)	1,000
	Taping code	TL
	Marking	RCJ220N25

• Absolute maximum ratings($T_a = 25$ °C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	250	V	
Continuous drain current	T _c = 25°C	I _D *1	±22	А
	T _c = 100°C	I _D *1	±11.9	А
Pulsed drain current	I _{D,pulse} *2	±88	А	
Gate - Source voltage	V_{GSS}	±30	V	
Avalanche energy, single pulse	E _{AS} *3	36.8	mJ	
Avalanche current		I _{AR} *3	11	А
T _c = 25°C		P _D	166	W
Power dissipation $T_a = 25^{\circ}C^{*4}$		P _D	1.56	W
Junction temperature	T _j	150	°C	
Range of storage temperature	T _{stg}	-55 to +150	°C	

●Thermal resistance

Parameter	Symbol	Values			Unit
Parameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	-	0.75	°C/W
Thermal resistance, junction - ambient *4	R_{thJA}	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol Conditions		Values			Unit	
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	UIIIL	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	250	-	-	V	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 250V, V_{GS} = 0V$ $T_j = 25^{\circ}C$	ı	1	25	μΑ	
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	1	-	±100	nA	
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	3.0	-	5.0	V	
		$V_{GS} = 10V, I_D = 11A$	-	105	140		
Static drain - source on - state resistance	R _{DS(on)} *5	$V_{GS} = 10V, I_D = 11A$ $T_j = 125^{\circ}C$	-	230	320	mΩ	
Forward transfer admittance	g _{fs}	$V_{DS} = 10V, I_{D} = 11A$	6	12	-	S	

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii e lei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	$V_{GS} = 0V$	ı	3200	ı	
Output capacitance	C _{oss}	V _{DS} = 25V	-	170	1	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	100	1	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 125V, V_{GS} = 10V$	-	45	1	
Rise time	t _r *5	I _D = 11A	-	100	1	ne
Turn - off delay time	t _{d(off)} *5	$R_L = 12\Omega$	-	75	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	40	-	

• Gate Charge characteristics ($T_a = 25$ °C)

Parameter	Symbol	Conditions		Values		Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	V _{DD} ≃ 125V	-	60	-	
Gate - Source charge	Q _{gs} *5	I _D = 22A	-	15	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	20	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 125V, I_D = 22A$	-	7.4	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	ameter Symbol Conditions		Min.	Тур.	Max.	Offic
Continuous source current	I _S *1	T _c = 25°C	-	1	22	Α
Pulsed source current	I _{SM} *2	1 _c = 23 0	-	-	88	Α
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 22A$	-	-	1.5	V
Reverse recovery time	t _{rr} *5	I _S = 11A	-	140	-	ns
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/μs	-	660	-	nC

^{*1} Limited only by maximum temperature allowed.

*5 Pulsed

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L $^{\simeq}$ 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T $_{j}$ = 25°C

^{*4} Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

Fig.1 Power Dissipation Derating Curve

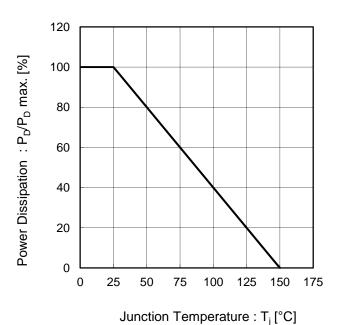
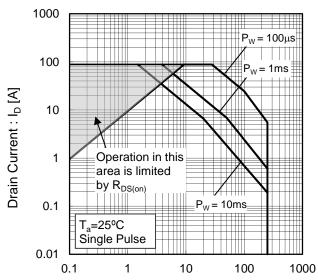
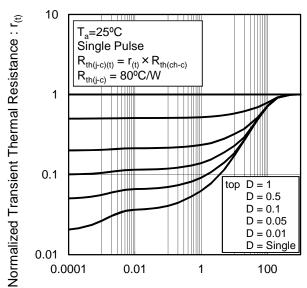


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width : $P_W[s]$

Fig.4 Avalanche Current vs Inductive Load

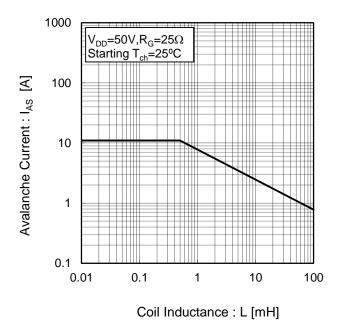
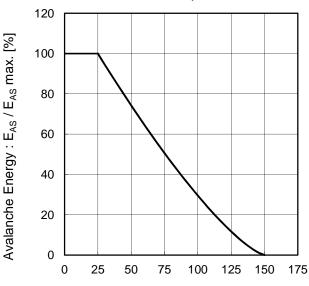
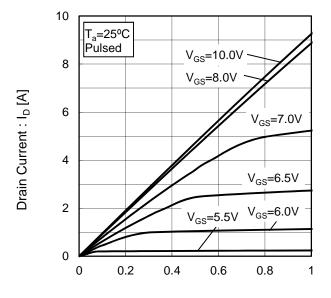


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



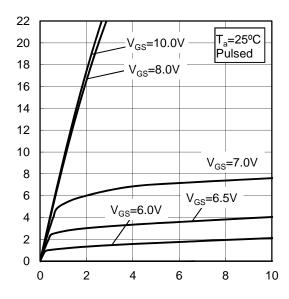
Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.7 Typical Output Characteristics(II)

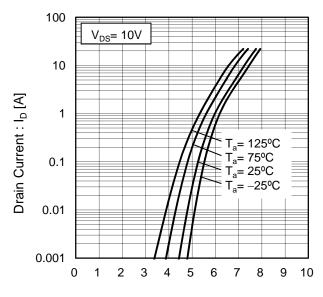


Drain - Source Voltage : V_{DS} [V]

Drain Current : I_D [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 340 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ $I_D = 1mA$ 320 300 $: V_{(BR)DSS}[V]$ 280 260 240 220 -50 0 50 100 150 Junction Temperature : T_i [°C]

Fig.9 Typical Transfer Characteristics



Gate - Source Voltage : V_{GS} [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature

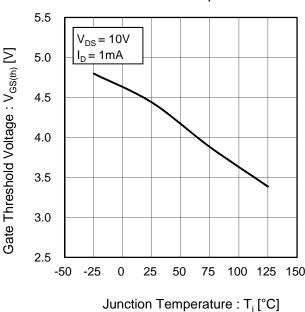
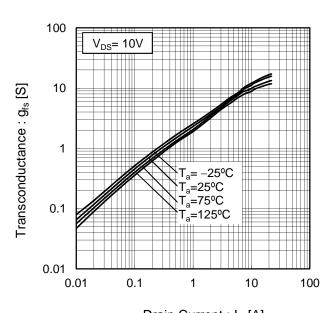


Fig.11 Transconductance vs. Drain Current



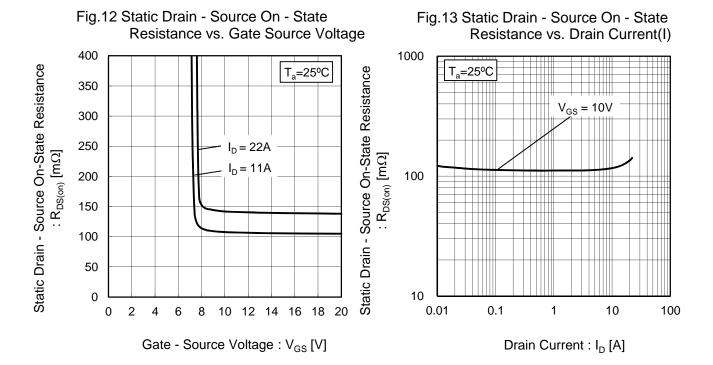
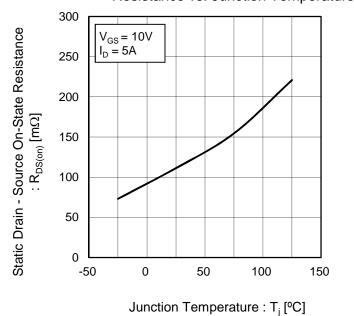


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



Resistance vs. Drain Current(II)

1000 $V_{GS} = 10V$ V_{G

Drain Current : I_D [A]

Fig.15 Static Drain - Source On - State

Fig.16 Drain Current Derating Curve

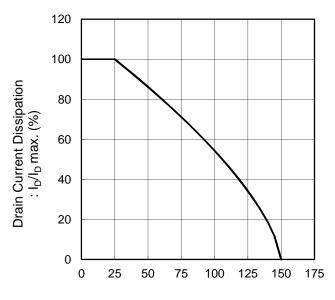
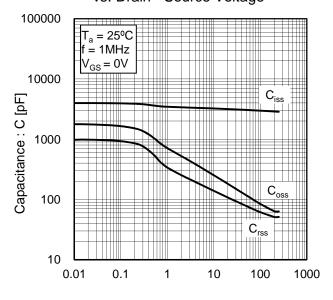
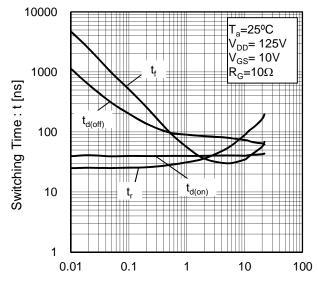


Fig.17 Typical Capacitance vs. Drain - Source Voltage



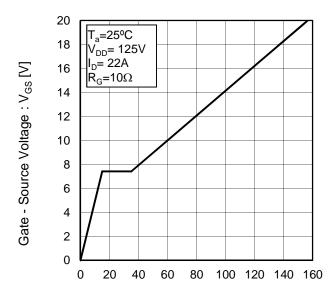
Drain - Source Voltage : V_{DS} [V]

Fig.18 Switching Characteristics



Drain Current : I_D [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]

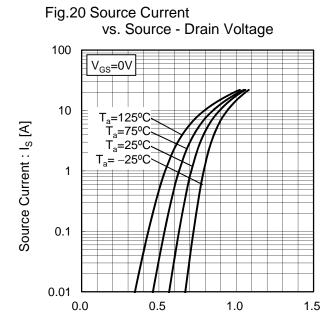


Fig21 Reverse Recovery Time

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

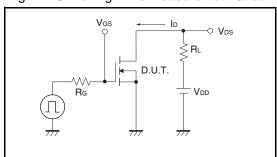


Fig.2-1 Gate Charge Measurement Circuit

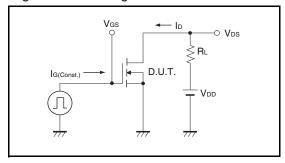


Fig.3-1 Avalanche Measurement Circuit

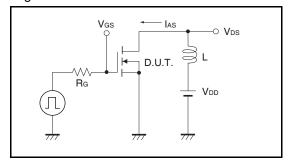


Fig.1-2 Switching Waveforms

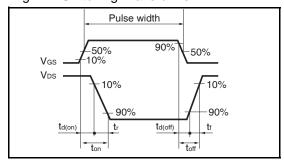


Fig.2-2 Gate Charge Waveform

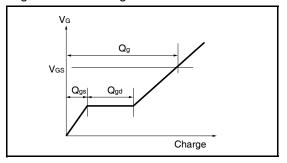
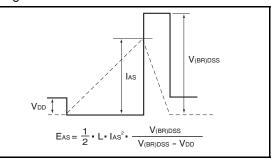
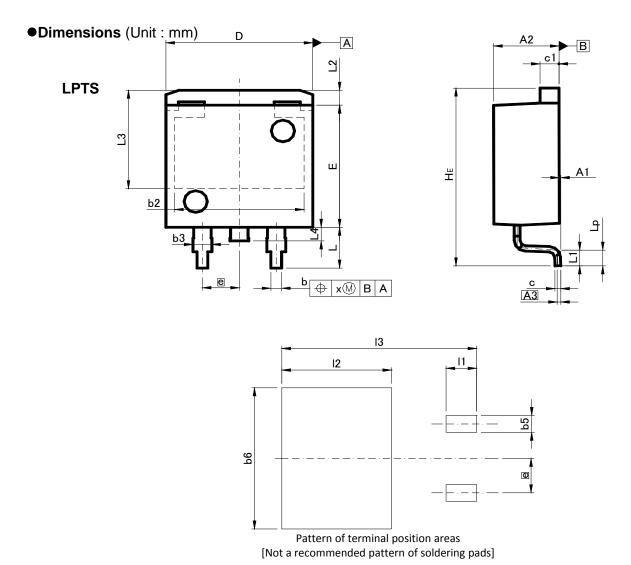


Fig.3-2 Avalanche Waveform





DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.	25	0.0	110
b	0.68	0.98	0.027	0.039
b2	8.	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	0.90	1.50	0.035	0.059
L2	1.10		0.043	
L3	7.25		0.285	
L4	1.	00	0.0	39
Lp	0.90	1.50	0.035	0.059
X	_	0.25	-	0.010

DIM	MILIMETERS IN		INC	HES
DIM	MIN	MAX	MIN	MAX
bb	-	1.23	-	0.049
b6	-	10.40	-	0.409
1	-	2.10	1	0.083
12	_	7.55	ı	0.297
13	_	13.40	_	0.528

Dimension in mm / inches

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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
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 - [d] the Products are exposed to high Electrostatic
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